This is a published notice on the Find a Tender service: <a href="https://www.find-tender.service.gov.uk/Notice/027974-2021">https://www.find-tender.service.gov.uk/Notice/027974-2021</a>

Contract

# **Supply of Semiconductor Dicing and Grinding Systems**

Swansea University

F03: Contract award notice

Notice identifier: 2021/S 000-027974

Procurement identifier (OCID): ocds-h6vhtk-02cb8f

Published 8 November 2021, 3:35pm

# **Section I: Contracting authority**

### I.1) Name and addresses

Swansea University

Procurement - VC's Office, Swansea University, Singleton Park

Swansea

SA28PP

#### Contact

James Thomas

#### **Email**

procurement@swansea.ac.uk

#### **Telephone**

+44 1792602779

#### Country

**United Kingdom** 

**NUTS** code

UKL18 - Swansea

Internet address(es)

Main address

www.swansea.ac.uk

Buyer's address

https://www.sell2wales.gov.wales/search/Search\_AuthProfile.aspx?ID=AA0345

### I.2) Information about joint procurement

The contract is awarded by a central purchasing body

### I.4) Type of the contracting authority

Body governed by public law

I.5) Main activity

Education

# **Section II: Object**

### II.1) Scope of the procurement

II.1.1) Title

Supply of Semiconductor Dicing and Grinding Systems

Reference number

SU154(21)

#### II.1.2) Main CPV code

• 38000000 - Laboratory, optical and precision equipments (excl. glasses)

#### II.1.3) Type of contract

**Supplies** 

#### II.1.4) Short description

This Tender Specification is for the supply and installation of a Wafer Dicing System and a Wafer Grinding System. These systems will be of strategic importance in expanding the capabilities that the CISM will be able to provide, and reliability of the equipment is paramount to maintaining and supporting the wide array of experimental work that will be conducted within the facility.

This requirement is split into two separate lots

#### II.1.6) Information about lots

This contract is divided into lots: Yes

#### II.1.7) Total value of the procurement (excluding VAT)

Value excluding VAT: £385,000

### II.2) Description

#### II.2.1) Title

Wafer Dicing System

Lot No

1

#### II.2.2) Additional CPV code(s)

• 38000000 - Laboratory, optical and precision equipments (excl. glasses)

#### II.2.3) Place of performance

**NUTS** codes

- UKL18 Swansea
- UKL17 Bridgend and Neath Port Talbot
- UKL21 Monmouthshire and Newport

Main site or place of performance

to be delivered to Swansea University Bay Campus or Newport Wafer Fab (to be determined prior to delivery)

#### II.2.4) Description of the procurement

This Tender Specification is for the supply and installation of a Wafer Dicing System and a Wafer Grinding System. These systems will be of strategic importance in expanding the capabilities that the CISM will be able to provide, and reliability of the equipment is paramount to maintaining and supporting the wide array of experimental work that will be conducted within the facility.

#### II.2.5) Award criteria

Quality criterion - Name: Technical / Weighting: 70

Price - Weighting: 30

#### II.2.11) Information about options

Options: No

#### II.2.13) Information about European Union Funds

The procurement is related to a project and/or programme financed by European Union funds: No

#### II.2.14) Additional information

Funding for this procurement has been secured from the Driving the Electric Revolution (DER) Industrialisation Centres Programme via Innovate UK.

### II.2) Description

#### II.2.1) Title

Wafer Grinding System

Lot No

2

#### II.2.2) Additional CPV code(s)

• 38000000 - Laboratory, optical and precision equipments (excl. glasses)

#### II.2.3) Place of performance

**NUTS** codes

• UKL21 - Monmouthshire and Newport

Main site or place of performance

Newport Wafer Fab

#### II.2.4) Description of the procurement

This procurement is for the supply and installation of a Wafer Grinding System. This will be of strategic importance in expanding the capabilities that the CISM will be able to provide, and reliability of the equipment is paramount to maintaining and supporting the wide array of experimental work that will be conducted within the facility.

#### II.2.5) Award criteria

Quality criterion - Name: Technical / Weighting: 70

Price - Weighting: 30

#### II.2.11) Information about options

Options: No

#### II.2.13) Information about European Union Funds

The procurement is related to a project and/or programme financed by European Union funds: No

#### II.2.14) Additional information

Funding for this procurement has been secured from the Driving the Electric Revolution (DER) Industrialisation Centres Programme via Innovate UK.

# Section IV. Procedure

### **IV.1) Description**

#### IV.1.1) Type of procedure

Open procedure

#### IV.1.8) Information about the Government Procurement Agreement (GPA)

The procurement is covered by the Government Procurement Agreement: Yes

### IV.2) Administrative information

#### IV.2.1) Previous publication concerning this procedure

Notice number: <u>2021/S 000-017441</u>

### Section V. Award of contract

#### Lot No

1

#### **Title**

Wafer Dicing System

A contract/lot is awarded: Yes

### V.2) Award of contract

#### V.2.1) Date of conclusion of the contract

19 October 2021

#### V.2.2) Information about tenders

Number of tenders received: 2

Number of tenders received from SMEs: 0

Number of tenders received from tenderers from other EU Member States: 2

Number of tenders received from tenderers from non-EU Member States: 0

Number of tenders received by electronic means: 2

The contract has been awarded to a group of economic operators: No

#### V.2.3) Name and address of the contractor

Disco HI-TEC UK LTD

Unit 34, Basepoint Business & Innovation Centre, Metcalf Way

Crawley

RH117XX

Telephone

+44 4989909030

Country

**United Kingdom** 

**NUTS** code

• UKJ2 - Surrey, East and West Sussex

The contractor is an SME

No

#### V.2.4) Information on value of contract/lot (excluding VAT)

Initial estimated total value of the contract/lot: £80,000

Total value of the contract/lot: £103,982

### Section V. Award of contract

#### Lot No

2

#### **Title**

Wafer Grinding System

A contract/lot is awarded: Yes

### V.2) Award of contract

#### V.2.1) Date of conclusion of the contract

19 October 2021

### V.2.2) Information about tenders

Number of tenders received: 1

Number of tenders received from SMEs: 0

Number of tenders received from tenderers from other EU Member States: 1

Number of tenders received from tenderers from non-EU Member States: 0

Number of tenders received by electronic means: 1

The contract has been awarded to a group of economic operators: No

#### V.2.3) Name and address of the contractor

Disco HI-TEC UK LTD

Unit 34, Basepoint Business & Innovation Centre, Metcalf Way

Crawley

RH117XX

Telephone

#### +44 4989909030

Country

United Kingdom

**NUTS** code

• UKJ2 - Surrey, East and West Sussex

The contractor is an SME

No

# V.2.4) Information on value of contract/lot (excluding VAT)

Initial estimated total value of the contract/lot: £250,000

Total value of the contract/lot: £278,592

# **Section VI. Complementary information**

# VI.3) Additional information

(WA Ref:115452)

# VI.4) Procedures for review

VI.4.1) Review body

**High Court** 

Royal Courts of Justice, The Strand

London

WC2A 2LL

Telephone

+44 2079477501

Country

United Kingdom